

## **What is claimed is:**

- [Claim 1]** 1. A package structure comprising:  
a lead frame having a plurality of first leads, each of which includes a first recession;  
at least a first device; and  
a plurality of solder joints respectively positioned in the first recessions for connecting the first device to the lead frame.
- [Claim 2]** 2. The package structure of claim 1 wherein the first device is a semiconductor chip.
- [Claim 3]** 3. The package structure of claim 1 wherein the first device is a passive device.
- [Claim 4]** 4. The package structure of claim 3 wherein the passive device is an electrical resistor, a capacitor, or an inductor.
- [Claim 5]** 5. The package structure of claim 3 wherein the lead frame comprises a plurality of second leads.
- [Claim 6]** 6. The package structure of claim 5 wherein the package structure further comprises a plurality of leading wires and at least a second device for connecting the leading wire to the second leads.
- [Claim 7]** 7. The package structure of claim 3 wherein the lead frame comprises a plurality of second leads, each of which includes a second recession.

**[Claim 8]** 8. The package structure of claim 7 wherein the package structure comprises at least one second device and a plurality of second solder joints respectively positioned in the second recessions for connecting the second device to the lead frame.

**[Claim 9]** 9. The package structure of claim 8 wherein the second device is a semiconductor die and the second solder joint is composed of tin or tin alloy.

**[Claim 10]** 10. The package structure of claim 2 wherein the lead frame comprises a die pad connected to the first device for radiating the heat produced by the first device by serving as a heat sink.

**[Claim 11]** 11. The package structure of claim 10 wherein the chip sink includes a ground pad connected to both ground and the first device.

**[Claim 12]** 12. The package structure of claim 1 wherein the first solder joint is composed of tin or tin alloy.